

UHV Technologies, Inc. introduces low cost vacuum systems for nanotechnology R&D at NanoTx 2006.

Ideal for Nano-Materials R&D at Universities and Nanotechnology Companies

* **AFFORDABLE**

* **FLEXIBLE**

* **UPGRADABLE**

..yet state-of-the-art!

Applications

- * R & D
- * Small Scale Production
- * Specialized Processes



Starting
At
\$50,000

FEATURES

- * 2-8 inch wafer capability
- * 12 inch and 14 inch cube chamber
- * Industrial PLC and PC based controller
- * Mechanical and turbo pumps
- * Very small foot print-24 inch x 30 inch
- * Load-locks provision for Cluster Tool capability
- * Four process power supplies are standard
- * Extensive options for sources and fixturing

PROCESSES

- * Plasma Enhanced CVD (PECVD)
- * Hot Filament PECVD
- * DC and RF Multi-Source Bias Sputtering
- * Plasma and Reactive Ion Etching (RIE)
- * Ion Beam Deposition (IBD)
- * Carbon Arc and Thermal Evaporation
- * Atomic Layer epitaxy (ALE)
- * Pulsed Laser Deposition (PLD)